

## ABSTRACT

The structure and method of a Ball-Grid Array or Land-Grid Array plastic integrated circuit (IC) device are described, which have gold bumps on the chip contact pads, spaced apart by less than 100  $\mu\text{m}$  center to center, flip-chip attached to a thin-film plastic substrate. An overmold package provides stability for solder ball attachment to outside parts (FIG. 1). An optional non-conductive polymer adhesive, used as a bump underfill, provides additional package rigidity.

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